

Title (en)

Method of manufacturing an integrated circuit using chemical mechanical polishing and fixture for chemical mechanical polishing

Title (de)

Chemisch-mechanisches Polierverfahren zur Herstellung eines integrierten Schaltkreises und zugehörige Haltevorrichtung

Title (fr)

Procédé de polissage mécano-chimique pour la fabrication d'un circuit intégré et dispositif de fixation pour polissage mécano-chimique

Publication

EP 0923122 B1 20110907 (EN)

Application

EP 98309597 A 19981124

Priority

- US 98210997 A 19971201
- US 98094397 A 19971201

Abstract (en)

[origin: EP0923122A2] A method of manufacturing integrated circuits using a carrier fixture. The carrier fixture does not include transport channels or openings for directing a slurry to a substrate being polished and, as a result, damage to the substrate is reduced because the edges adjacent to the substrate are eliminated. The present invention further provides a carrier fixture having an inner support (e.g., 130) coupled to a ring member (e.g., 120) that contacts a substrate (e.g., 200) during the CMP process. The present invention also provides a carrier fixture having inner (e.g., 130) and outer supports (e.g., 125) coupled to a ring member (e.g., 120). <IMAGE>

IPC 8 full level

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CPC (source: EP KR)

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